



BR6 Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 36.39%	Copper (Cu)	7440-50-8	1196.485	99.9645	363,783.82
	Phosphorus (P)	7723-14-0	0.020	0.0017	6.1
	Arsenic (As)	7440-38-2	0.020	0.0017	6.1
	Tin (Sn)	7440-31-5	0.020	0.0017	6.1
	Oxygen (O)	7782-44-7	0.010	0.0008	3.0
	Sulfur (S)	7704-34-9	0.240	0.0201	73.0
	Iron (Fe)	7439-89-6	0.013	0.0011	4.0
	Nickel (Ni)	7440-02-0	0.006	0.0005	1.8
	Bismuth (Bi)	7440-69-9	0.040	0.0033	12.2
	Antimony (Sb)	1309-64-4	0.040	0.0033	12.2
	Lead (Pb)	7439-92-1	0.010	0.0008	3.0
	Zinc (Zn)	7440-66-6	0.006	0.0005	1.8
	Total		1,196.91		
Solder Wafer 0.47%	Lead (Pb)	7439-92-1	14.28	92.49	4,341.7
	Tin (Sn)	7440-31-5	0.77	4.99	234.1
	Silver (Ag)	7440-22-4	0.39	2.52	118.6
	Total		15.44		
Chip 0.49%	Silicon (Si)	7440-21-3	15.30	95.40	4,652.5
	Lead (Pb)	7439-92-1	0.74	4.60	224.3
	Total		16.04		
Case 22.33%	Epoxy	38891-59-7	734.33	100.00	223,268.5
	Total		734.33		
Potting 40.06%	Epoxy	38891-59-7	1,317.60	100.00	400,608.1
	Total		1,317.60		
Plating 0.26%	Tin (Sn)	7440-31-5	8.84	100.00	2,687.7
	Total		8.84		
	Total mass (mg)		3289.00		